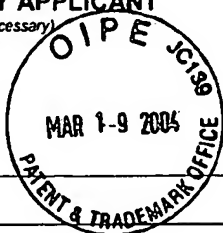


Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known	
	Application Number	10/023819
	Filing Date	December 21, 2001
	First Named Inventor	Chandran, Biju
	Group Art Unit	2827
	Examiner Name	Vigushin, John
Sheet 1 of 1	Attorney Docket No: 884.A27US1	



US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
BU	US-3,871,015	03/11/1975	Lin, Paul T.C., et al.	257	67779	08/14/1969
BU	US-4,481,403	11/06/1984	Del Monte, Lou A.	219	209	03/04/1983
BU	US-5,698,465	12/16/1997	Lynch, Brian, et al.	438	480 125	06/07/1995
BU	US-6,162,660	12/19/2000	Lafontaine, Jr., William R., et al.	438	108	05/03/1995
BU	US-6,170,155	01/09/2001	Marion, F., et al.	29	840	05/15/1997
BU	US-6,259,155	07/10/2001	Interrante, Mario J., et al.	257	690	04/12/1999
BU	US-6,310,403	10/30/2001	Zhang, C., et al.	257	786	08/31/2000
BU	US-6,330,967	12/18/2001	Milewski, Joseph M., et al.	228	180.22	03/13/1997
BU	US-6,395,124	05/28/2002	Oxman, J. D., et al.	156	275.5	07/30/1999

FOREIGN PATENT DOCUMENTS						
Examiner Initials *	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
BU	JP-08-332590	12/17/1996	Bitailou, A., et al.	B23K	35/22	
BU	JP-09-275107	10/21/1997	Ozoe, Shoji	H01L	21/321	
BU	JP-10-12659	01/16/1998	Yamamoto, Michihiko	H01L	21/60	
BU	JP-59-177957	10/08/1984	Kano, Hiroshi, et al.	H01L	23/48	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials *	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ⁴
BU		ANONYMOUS, "Solder ball for semiconductor chip - has height increased so that stress caused by difference in thermal expansion between chip and substrate is minimised", Research Disclosure RD-291011, Derwent 1988-255069, (7/10/88), 2 pages	

EXAMINER John B. Vigushin DATE CONSIDERED May 31, 2004

Substitute Disclosure Statement Form (PTO-1449)
* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached

Paper No. 0304